

Application No.
10/569,942

Group Unknown	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80	81	82	83	84	85	86	87	88	89	90	91	92	93	94	95	96	97	98	99	100
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[illegible][illegible]

	1	U.S. Patent Application No. 11/851,065 (NISHIHATA et al.), which was filed on September 6, 2007 and entitled, "BONDED WAFER AND METHOD OF MANUFACTURING THE SAME."

DATE CONSIDERED

{P29123 00362820.DOC}